PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		ADG/21/12670
1.3 Title of PCN		STDxx (MOSFET Products in DPAK): Activation of TFME (TongFu former Nantong Fujitsu) as Second Source of Assembly and Final Testing
1.4 Product Category		see list
1.5 Issue date		2021-04-03

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	NEMETH KRISZTINA	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Mario ASTUTI	
2.1.2 Marketing Manager	Anna RANIOLO,Michele SCUTO	
2.1.3 Quality Manager	Vincenzo MILITANO	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)		

4. Description of change			
	Old	New	
4.1 Description	ST Shenzhen - Assembly and Final testing	ST Shenzhen - Assembly and Final Testing Subcontractor TFME (TongFu former Nantong Fujitsu) - Assembly and Final Testing	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact		

5. Reason / motivation for change		
5.1 Motivation	Capacity Increase	
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change		
6.1 Description	Dedicated Finished Good Codes	

7. Timing / schedule		
7.1 Date of qualification results	2021-03-19	
7.2 Intended start of delivery	2021-06-30	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description	12670 Validation.zip		
8.2 Qualification report and qualification results		Issue Date	2021-04-03

9. Attachments (additional documentations)

12670 Public product.pdf 12670 Validation.zip 12670 Details.pdf

 10. Affected parts

 10. 1 Current
 10.2 New (if applicable)

 10.1.1 Customer Part No
 10.1.2 Supplier Part No

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 10.1.2 Supplier Part No

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